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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280c-3b256c

June 2013

Data Sheet DS1002

Features

- **Non-volatile, Infinitely Reconfigurable**
 - Instant-on – powers up in microseconds
 - Single chip, no external configuration memory required
 - Excellent design security, no bit stream to intercept
 - Reconfigure SRAM based logic in milliseconds
 - SRAM and non-volatile memory programmable through JTAG port
 - Supports background programming of non-volatile memory
- **Sleep Mode**
 - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
 - In-field logic update while system operates
- **High I/O to Logic Density**
 - 256 to 2280 LUT4s
 - 73 to 271 I/Os with extensive package options
 - Density migration supported
 - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
 - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
 - Up to 7.7 Kbits distributed RAM
 - Dedicated FIFO control logic

Table 1-1. MachXO Family Selection Guide

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

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The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to V_{CCIO} . The I/O pins will maintain the blank configuration until V_{CC} , V_{CCAUX} and V_{CCIO} have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

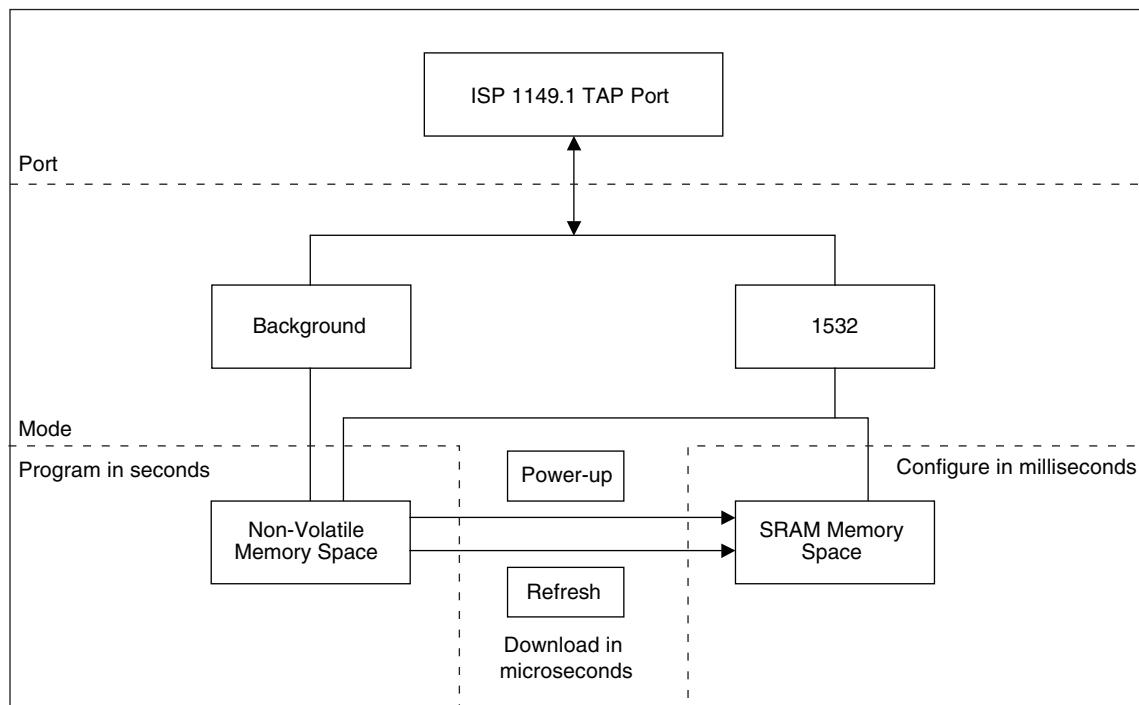
The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Figure 2-22. MachXO Configuration and Programming



Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

sysIO Recommended Operating Conditions

Standard	V_{CCIO} (V)		
	Min.	Typ.	Max.
LVC MOS 3.3	3.135	3.3	3.465
LVC MOS 2.5	2.375	2.5	2.625
LVC MOS 1.8	1.71	1.8	1.89
LVC MOS 1.5	1.425	1.5	1.575
LVC MOS 1.2	1.14	1.2	1.26
LV TTL	3.135	3.3	3.465
PCI ³	3.135	3.3	3.465
LVDS ^{1,2}	2.375	2.5	2.625
LVPECL ¹	3.135	3.3	3.465
BLVDS ¹	2.375	2.5	2.625
RS DS ¹	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers

3. Input on the top bank of the MachXO1200 and MachXO2280 only.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} ¹ (mA)	I_{OH} ¹ (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVC MOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LV TTL	-0.3	0.8	2.0	3.6	0.4	2.4	16	-16
					0.4	V_{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("E" Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.

MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTL33	LVTTL	0.01	0.01	0.01	ns
LVCMOS33	LVCMOS 3.3	0.01	0.01	0.01	ns
LVCMOS25	LVCMOS 2.5	0.00	0.00	0.00	ns
LVCMOS18	LVCMOS 1.8	0.07	0.08	0.10	ns
LVCMOS15	LVCMOS 1.5	0.14	0.17	0.19	ns
LVCMOS12	LVCMOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTL33_4mA	LVTTL 4mA drive	0.04	0.04	0.05	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.07	0.08	ns
LVTTL33_12mA	LVTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTL33_16mA	LVTTL 16mA drive	0.50	0.60	0.70	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVCMOS33_14mA	LVCMOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVCMOS25_14mA	LVCMOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVCMOS18_14mA	LVCMOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.
2. LVCMOS timing is measured with the load specified in Switching Test Conditions table.
3. All other standards tested according to the appropriate specifications.
4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

Rev. A 0.19

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	55	%
t_{PH}^4	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}^1	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-120	ps
		$f_{OUT} < 100$ MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_W	Output Clock Pulse Width	At 90% or 10% ³	1	—	ns
t_{LOCK}^2	PLL Lock-in Time		—	150	μs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-200	ps
		$f_{OUT} < 100$ MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19

Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTL and LVCMOS Standards

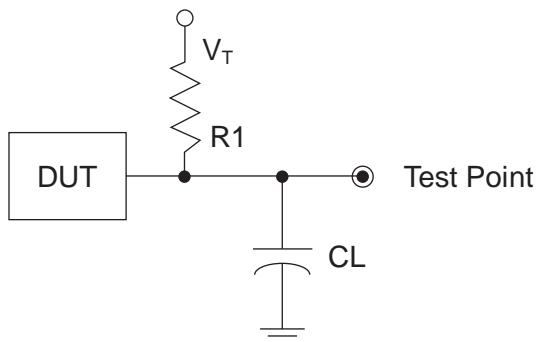


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	C _L	Timing Ref.	V _T
LVTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = V _{CCIO} /2	—
			LVCMOS 1.8 = V _{CCIO} /2	—
			LVCMOS 1.5 = V _{CCIO} /2	—
			LVCMOS 1.2 = V _{CCIO} /2	—
LVTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V _{OL}
LVTTL and LVCMOS 3.3 (Z -> L)				V _{OH}
Other LVCMOS (Z -> H)			V _{CCIO} /2	V _{OL}
Other LVCMOS (Z -> L)			V _{CCIO} /2	V _{OH}
LVTTL + LVCMOS (H -> Z)			V _{OH} - 0.15	V _{OL}
LVTTL + LVCMOS (L -> Z)			V _{OL} - 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Pin Information Summary

Pin Type	LCMxo256C/E		LCMxo640C/E				
	100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O	78	78	74	113	74	101	159
Differential Pair User I/O ¹	38	38	17	43	17	42	79
Muxed	6	6	6	6	6	6	6
TAP	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)	5	5	5	5	5	5	5
VCC	2	2	2	4	2	4	4
VCCAUX	1	1	1	2	1	2	2
VCCIO	Bank0	3	3	2	2	2	4
	Bank1	3	3	2	2	2	4
	Bank2	—	—	2	2	2	4
	Bank3	—	—	2	2	2	4
GND	8	8	10	12	10	12	18
NC	0	0	0	0	0	0	52
Single Ended/Differential I/O per Bank	Bank0	41/20	41/20	18/5	29/10	18/5	26/11
	Bank1	37/18	37/18	21/4	30/11	21/4	27/12
	Bank2	—	—	14/2	24/9	14/2	21/9
	Bank3	—	—	21/6	30/13	21/6	27/10
							40/20

1. These devices support emulated LVDS outputs.pLVDS inputs are not supported.

Pin Type	LCMxo1200C/E				LCMxo2280C/E				
	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O	73	113	101	211	73	113	101	211	271
Differential Pair User I/O ¹	27	48	42	105	30	47	41	105	134
Muxed	6	6	6	6	6	6	6	6	6
TAP	4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)	5	5	5	5	5	5	5	5	5
VCC	4	4	4	4	2	4	4	4	6
VCCAUX	2	2	2	2	2	2	2	2	2
VCCIO	Bank0	1	1	1	2	1	1	1	2
	Bank1	1	1	1	2	1	1	1	2
	Bank2	1	1	1	2	1	1	1	2
	Bank3	1	1	1	2	1	1	1	2
	Bank4	1	1	1	2	1	1	1	2
	Bank5	1	1	1	2	1	1	1	2
	Bank6	1	1	1	2	1	1	1	2
	Bank7	1	1	1	2	1	1	1	2
GND	8	12	12	18	8	12	12	18	24
NC	0	0	0	0	0	0	0	0	0
Single Ended/Differential I/O per Bank	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13
	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14
	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13

1. These devices support on-chip LVDS buffers for left and right I/O Banks.

Power Supply and NC (Cont.)

Signal	132 csBGA ¹	256 caBGA / 256 ftBGA ¹	324 ftBGA ¹
VCC	H3, P6, G12, C7	G7, G10, K7, K10	F14, G11, G9, H7, L7, M9
VCCIO0	LCMxo640: B11, C5 LCMxo1200/2280: C5	LCMxo640: F8, F7, F9, F10 LCMxo1200/2280: F8, F7	G8, G7
VCCIO1	LCMxo640: L12, E12 LCMxo1200/2280: B11	LCMxo640: H11, G11, K11, J11 LCMxo1200/2280: F9, F10	G12, G10
VCCIO2	LCMxo640: N2, M10 LCMxo1200/2280: E12	LCMxo640: L9, L10, L8, L7 LCMxo1200/2280: H11, G11	J12, H12
VCCIO3	LCMxo640: D2, K3 LCMxo1200/2280: L12	LCMxo640: K6, J6, H6, G6 LCMxo1200/2280: K11, J11	L12, K12
VCCIO4	LCMxo640: None LCMxo1200/2280: M10	LCMxo640: None LCMxo1200/2280: L9, L10	M12, M11
VCCIO5	LCMxo640: None LCMxo1200/2280: N2	LCMxo640: None LCMxo1200/2280: L8, L7	M8, R9
VCCIO6	LCMxo640: None LCMxo1200/2280: K3	LCMxo640: None LCMxo1200/2280: K6, J6	M7, K7
VCCIO7	LCMxo640: None LCMxo1200/2280: D2	LCMxo640: None LCMxo1200/2280: H6, G6	H6, J7
VCCAUX	P7, A7	T9, A8	M10, F9
GND ²	F1, P9, J14, C9, A10, B4, L13, D13, P2, N11, E1, L2	A1, A16, F11, G8, G9, H7, H8, H9, H10, J7, J8, J9, J10, K8, K9, L6, T1, T16	E14, F16, H10, H11, H8, H9, J10, J11, J4, J8, J9, K10, K11, K17, K8, K9, L10, L11, L8, L9, N2, P14, P5, R7
NC ³	—	LCMxo640: E4, E5, F5, F6, C3, C2, G4, G5, H4, H5, K5, K4, M5, M4, P2, P3, N5, N6, M7, M8, N10, N11, R15, R16, P15, P16, M11, L11, N12, N13, M13, M12, K12, J12, F12, F13, E12, E13, D13, D14, B15, A15, C14, B14, E11, E10, E7, E6, D4, D3, B3, B2 LCMxo1200: None LCMxo2280: None	—

1. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
2. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
3. NC pins should not be connected to any active signals, VCC or GND.

**LCMXX640, LCMXO1200 and LCMXO2280 Logic Signal Connections:
144 TQFP**

Pin Number	LCMXX640				LCMXX1200				LCMXX2280				
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	
1	PL2A	3		T	PL2A	7			T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7			C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7			T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7			C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7			T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7			C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7			T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7			C*	PL4B	7		C*
9	PL4A	3			PL4C	7				PL4C	7		
10	VCCIO3	3			VCCIO7	7				VCCIO7	7		
11	GNDIO3	3			GNDIO7	7				GNDIO7	7		
12	PL4D	3			PL5C	7				PL6C	7		
13	PL5A	3		T	PL6A	7			T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN		C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7				PL7D	7		
16	GND	-			GND	-				GND	-		
17	PL6C	3		T	PL7C	7			T	PL9C	7		T
18	PL6D	3		C	PL7D	7			C	PL9D	7		C
19	PL7A	3		T	PL10A	6			T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6			C*	PL13B	6		C*
21	VCC	-			VCC	-				VCC	-		
22	PL8A	3		T	PL11A	6			T*	PL13D	6		
23	PL8B	3		C	PL11B	6			C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL			PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6				PL15B	6		
26	VCCIO3	3			VCCIO6	6				VCCIO6	6		
27	GNDIO3	3			GNDIO6	6				GNDIO6	6		
28	PL9D	3		C	PL13D	6				PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*		PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*		PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6			T	PL17C	6		T
32	PL11A	3		T	PL14D	6			C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*		PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*		PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6			T	PL19A	6		T
36	PL11D	3		C	PL16B	6			C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5				GNDIO5	5		
38	VCCIO2	2			VCCIO5	5				VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS			TMS	5	TMS	
40	PB2C	2			PB2C	5			T	PB2A	5		T
41	PB3A	2		T	PB2D	5			C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK			TCK	5	TCK	
43	PB3B	2		C	PB3A	5			T	PB3A	5		T
44	PB3C	2		T	PB3B	5			C	PB3B	5		C
45	PB3D	2		C	PB4A	5			T	PB4A	5		T
46	PB4A	2		T	PB4B	5			C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO			TDO	5	TDO	
48	PB4B	2		C	PB4D	5				PB4D	5		
49	PB4C	2		T	PB5A	5			T	PB5A	5		T
50	PB4D	2		C	PB5B	5			C	PB5B	5		C

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 144 TQFP (Cont.)**

Pin Number	LCMxo640				LCMxo1200				LCMxo2280				
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	
101	PR3D	1		C	PR4B	2			C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2			T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2			C	PR4D	2		C
104	PR2D	1		C	PR3C	2			T	PR4C	2		T
105	PR3A	1		T	PR3B	2			C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2			T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2			C	PR3B	2		C*
108	PR2A	1		T	PR2A	2			T	PR3A	2		T*
109	PT9F	0		C	PT11D	1			C	PT16D	1		C
110	PT9D	0		C	PT11C	1			T	PT16C	1		T
111	PT9E	0		T	PT11B	1			C	PT16B	1		C
112	PT9B	0		C	PT11A	1			T	PT16A	1		T
113	PT9C	0		T	PT10F	1			C	PT15D	1		C
114	PT9A	0		T	PT10E	1			T	PT15C	1		T
115	PT8C	0			PT10D	1			C	PT14B	1		C
116	PT8B	0		C	PT10C	1			T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1				VCCIO1	1		
118	GNDIO0	0			GNDIO1	1				GNDIO1	1		
119	PT8A	0		T	PT9F	1			C	PT12F	1		C
120	PT7E	0			PT9E	1			T	PT12E	1		T
121	PT7C	0			PT9B	1			C	PT12D	1		C
122	PT7A	0			PT9A	1			T	PT12C	1		T
123	GND	-			GND	-				GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***			PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1			C	PT9D	1		C
126	PT5C	0			PT7A	1			T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***			PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-				VCCAUX	-		
129	VCC	-			VCC	-				VCC	-		
130	PT4D	0			PT5D	0			C	PT7B	0		C
131	PT4B	0		C	PT5C	0			T	PT7A	0		T
132	PT4A	0		T	PT5B	0			C	PT6D	0		
133	PT3F	0			PT5A	0			T	PT6E	0		T
134	PT3D	0			PT4B	0				PT6F	0		C
135	VCCIO0	0			VCCIO0	0				VCCIO0	0		
136	GNDIO0	0			GNDIO0	0				GNDIO0	0		
137	PT3B	0		C	PT3D	0			C	PT4B	0		T
138	PT2F	0		C	PT3C	0			T	PT4A	0		C
139	PT3A	0		T	PT3B	0			C	PT3B	0		C
140	PT2D	0		C	PT3A	0			T	PT3A	0		T
141	PT2E	0		T	PT2D	0			C	PT2D	0		C
142	PT2B	0		C	PT2C	0			T	PT2C	0		T
143	PT2C	0		T	PT2B	0			C	PT2B	0		C
144	PT2A	0		T	PT2A	0			T	PT2A	0		T

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
E4	NC				E4	PL2A	7		T	E4	PL2A	7	LUM0_PLLT_FB_A	T
E5	NC				E5	PL2B	7		C	E5	PL2B	7	LUM0_PLLC_FB_A	C
F5	NC				F5	PL3A	7		T*	F5	PL3A	7		T*
F6	NC				F6	PL3B	7		C*	F6	PL3B	7		C*
F3	PL3A	3		T	F3	PL3C	7		T	F3	PL3C	7	LUM0_PLLT_IN_A	T
F4	PL3B	3		C	F4	PL3D	7		C	F4	PL3D	7	LUM0_PLLC_IN_A	C
E3	PL2C	3		T	E3	PL4A	7		T*	E3	PL4A	7		T*
E2	PL2D	3		C	E2	PL4B	7		C*	E2	PL4B	7		C*
C3	NC				C3	PL4C	7		T	C3	PL4C	7		T
C2	NC				C2	PL4D	7		C	C2	PL4D	7		C
B1	PL2A	3		T	B1	PL5A	7		T*	B1	PL5A	7		T*
C1	PL2B	3		C	C1	PL5B	7		C*	C1	PL5B	7		C*
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
D2	PL3C	3		T	D2	PL5C	7		T	D2	PL6C	7		T
D1	PL3D	3		C	D1	PL5D	7		C	D1	PL6D	7		C
F2	PL5A	3		T	F2	PL6A	7		T*	F2	PL7A	7		T*
G2	PL5B	3	GSRN	C	G2	PL6B	7	GSRN	C*	G2	PL7B	7	GSRN	C*
E1	PL4A	3		T	E1	PL6C	7		T	E1	PL7C	7		T
F1	PL4B	3		C	F1	PL6D	7		C	F1	PL7D	7		C
G4	NC				G4	PL7A	7		T*	G4	PL8A	7		T*
G5	NC				G5	PL7B	7		C*	G5	PL8B	7		C*
GND	GND	-			GND	GND	-			GND	GND	-		
G3	PL4C	3		T	G3	PL7C	7		T	G3	PL8C	7		T
H3	PL4D	3		C	H3	PL7D	7		C	H3	PL8D	7		C
H4	NC				H4	PL8A	7		T*	H4	PL9A	7		T*
H5	NC				H5	PL8B	7		C*	H5	PL9B	7		C*
-	-				VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
-	-				GND	GNDIO7	7			GND	GNDIO7	7		
G1	PL5C	3		T	G1	PL8C	7		T	G1	PL10C	7		T
H1	PL5D	3		C	H1	PL8D	7		C	H1	PL10D	7		C
H2	PL6A	3		T	H2	PL9A	6		T*	H2	PL11A	6		T*
J2	PL6B	3		C	J2	PL9B	6		C*	J2	PL11B	6		C*
J3	PL7C	3		T	J3	PL9C	6		T	J3	PL11C	6		T
K3	PL7D	3		C	K3	PL9D	6		C	K3	PL11D	6		C
J1	PL6C	3		T	J1	PL10A	6		T*	J1	PL12A	6		T*
-	-				VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
-	-				GND	GNDIO6	6			GND	GNDIO6	6		
K1	PL6D	3		C	K1	PL10B	6		C*	K1	PL12B	6		C*
K2	PL9A	3		T	K2	PL10C	6		T	K2	PL12C	6		T
L2	PL9B	3		C	L2	PL10D	6		C	L2	PL12D	6		C
L1	PL7A	3		T	L1	PL11A	6		T*	L1	PL13A	6		T*
M1	PL7B	3		C	M1	PL11B	6		C*	M1	PL13B	6		C*
P1	PL8D	3		C	P1	PL11D	6		C	P1	PL14D	6		C
N1	PL8C	3	TSALL	T	N1	PL11C	6	TSALL	T	N1	PL14C	6	TSALL	T
L3	PL10A	3		T	L3	PL12A	6		T*	L3	PL15A	6		T*
M3	PL10B	3		C	M3	PL12B	6		C*	M3	PL15B	6		C*
M2	PL9C	3		T	M2	PL12C	6		T	M2	PL15C	6		T
N2	PL9D	3		C	N2	PL12D	6		C	N2	PL15D	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1		T	J13	PR11A	3			J13	PR14A	3		T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		C	K14	PR10D	3			K14	PR13D	3		C
J14	PR8A	1		T	J14	PR10C	3			J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3			K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3			J15	PR13A	3		T*
-	-				GND	GNDIO3	3			GND	GNDIO3	3		
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3			K12	PR11D	3		C
J12	NC				J12	PR9C	3			J12	PR11C	3		T
J16	PR7B	1		C	J16	PR9B	3			J16	PR11B	3		C*
H16	PR7A	1		T	H16	PR9A	3			H16	PR11A	3		T*
H15	PR6B	1		C	H15	PR8D	2			H15	PR10D	2		C
G15	PR6A	1		T	G15	PR8C	2			G15	PR10C	2		T
H14	PR5D	1		C	H14	PR8B	2			H14	PR10B	2		C*
G14	PR5C	1		T	G14	PR8A	2			G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		C	H13	PR7D	2			H13	PR9D	2		C
H12	PR6C	1		T	H12	PR7C	2			H12	PR9C	2		T
G13	PR4D	1		C	G13	PR7B	2			G13	PR9B	2		C*
G12	PR4C	1		T	G12	PR7A	2			G12	PR9A	2		T*
G16	PR5B	1		C	G16	PR6D	2			G16	PR7D	2		C
F16	PR5A	1		T	F16	PR6C	2			F16	PR7C	2		T
F15	PR4B	1		C	F15	PR6B	2			F15	PR7B	2		C*
E15	PR4A	1		T	E15	PR6A	2			E15	PR7A	2		T*
E16	PR3B	1		C	E16	PR5D	2			E16	PR6D	2		C
D16	PR3A	1		T	D16	PR5C	2			D16	PR6C	2		T
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		C	D15	PR5B	2			D15	PR6B	2		C*
C15	PR2C	1		T	C15	PR5A	2			C15	PR6A	2		T*
C16	PR2B	1		C	C16	PR4D	2			C16	PR5D	2		C
B16	PR2A	1		T	B16	PR4C	2			B16	PR5C	2		T
F14	PR3D	1		C	F14	PR4B	2			F14	PR5B	2		C*
E14	PR3C	1		T	E14	PR4A	2			E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2			F12	PR4D	2		C
F13	NC				F13	PR3C	2			F13	PR4C	2		T
E12	NC				E12	PR3B	2			E12	PR4B	2		C*
E13	NC				E13	PR3A	2			E13	PR4A	2		T*
D13	NC				D13	PR2B	2			D13	PR3B	2		C*
D14	NC				D14	PR2A	2			D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2		
GND	GNDIO0	0			GND	GNDIO1	1			GND	GNDIO1	1		
VCCIO0	VCCIO0	0			VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
B15	NC				B15	PT11D	1			B15	PT16D	1		C
A15	NC				A15	PT11C	1			A15	PT16C	1		T
C14	NC				C14	PT11B	1			C14	PT16B	1		C
B14	NC				B14	PT11A	1			B14	PT16A	1		T
C13	PT9F	0		C	C13	PT10F	1			C13	PT15D	1		C
B13	PT9E	0		T	B13	PT10E	1			B13	PT15C	1		T

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
V10	PB9B	4		C
N10	PB9C	4		T
R10	PB9D	4		C
P10	PB10F	4	PCLK4_1***	C
T10	PB10E	4		T
U10	PB10D	4		C
V11	PB10C	4		T
U11	PB10B	4	PCLK4_0***	C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		T
U12	PB11A	4		T
R11	PB11B	4		C
GND	GND	-		
T12	PB11C	4		T
P11	PB11D	4		C
V12	PB12A	4		T
V13	PB12B	4		C
R12	PB12C	4		T
N11	PB12D	4		C
U13	PB12E	4		T
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		C
T13	PB13A	4		T
P12	PB13B	4		C
R13	PB13C	4		T
N12	PB13D	4		C
V15	PB14A	4		T
U14	PB14B	4		C
V16	PB14C	4		T
GND	GND	-		
T14	PB14D	4		C
U15	PB15A	4		T
V17	PB15B	4		C
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		T
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMxo1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMxo1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMxo1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMxo1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMxo1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMxo1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMxo1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMxo1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMxo1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMxo1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMxo1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMxo1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMxo1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMxo1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMxo2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMxo2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMxo2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMxo2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMxo2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMxo2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMxo2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMxo2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMxo2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMxo2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMxo2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMxo2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMxo2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMxo2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMxo2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMxo2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMxo2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

Conventional Packaging

Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3T100I	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	IND
LCMxo256C-4T100I	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	IND
LCMxo256C-3M100I	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	IND
LCMxo256C-4M100I	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3T100I	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	IND
LCMxo640C-4T100I	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	IND
LCMxo640C-3M100I	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	IND
LCMxo640C-4M100I	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	IND
LCMxo640C-3T144I	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo640C-4T144I	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo640C-3M132I	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo640C-4M132I	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo640C-3B256I	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	IND
LCMxo640C-4B256I	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	IND
LCMxo640C-3FT256I	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	IND
LCMxo640C-4FT256I	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3T100I	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo1200C-4T100I	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo1200C-3T144I	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo1200C-4T144I	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo1200C-3M132I	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo1200C-4M132I	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo1200C-3B256I	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo1200C-4B256I	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo1200C-3FT256I	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo1200C-4FT256I	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100I	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo2280C-4T100I	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo2280C-3T144I	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo2280C-4T144I	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo2280C-3M132I	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo2280C-4M132I	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo2280C-3B256I	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo2280C-4B256I	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo2280C-3FT256I	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo2280C-4FT256I	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND
LCMxo2280C-3FT324I	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	IND
LCMxo2280C-4FT324I	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	IND

Date	Version	Section	Change Summary
November 2006	02.3	DC and Switching Characteristics	Corrections to MachXO "C" Sleep Mode Timing table - value for $t_{WSLEEPN}$ (400ns) changed from max. to min. Value for t_{WAWAKE} (100ns) changed from min. to max.
			Added Flash Download Time table.
December 2006	02.4	Architecture	EBR Asynchronous Reset section added.
		Pinout Information	Power Supply and NC table: Pin/Ball orientation footnotes added.
February 2007	02.5	Architecture	Updated EBR Asynchronous Reset section.
August 2007	02.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table.
November 2007	02.7	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
June 2009	02.8	Introduction	Added 0.8-mm 256-pin caBGA package to MachXO Family Selection Guide table.
		Pinout Information	Added Logic Signal Connections table for 0.8-mm 256-pin caBGA package.
		Ordering Information	Updated Part Number Description diagram and Ordering Part Number tables with 0.8-mm 256-pin caBGA package information.
July 2010	02.9	DC and Switching Characteristics	Updated sysCLOCK PLL Timing table.
June 2013	03.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
		DC and Switching Characteristics	MachXO1200 and MachXO2280 Hot Socketing Specifications table – Removed footnote 4.
			Added MachXO Programming/Erase Specifications table.